$V_{RRM} = 2500 V$

 $I_{FAVM} = 490 A$

 $I_{FSM} = 8.5 \text{ kA}$

 $V_{F0} = 1.4 V$

 $r_F = 0.52 \text{ m}\Omega$

 $V_{DClink} = 1100 V$

Fast Recovery Diode

5SDF 05D2501

Doc. No. 5SYA1112-03 Sep. 01

- · Patented free-floating silicon technology
- Low switching losses
- Optimized for use as snubber diode in GTO converters
- Industry standard press-pack ceramic housing, hermetically cold-welded
- · Cosmic radiation withstand rating

Blocking

V_{RRM}	Repetitive peak reverse voltage	2500 V	Half sine wave, $t_P = 10 \text{ ms}$, $f = 50 \text{ Hz}$		
I _{RRM}	Repetitive peak reverse current	≤ 50 mA	$V_R = V_{RRM}$, $T_j = 125$ °C		
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	1100 V	100% Duty	Ambient cosmic radiation a sea level in open air.	
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	1500 V	5% Duty		

Mechanical data (see Fig. 8)

ш	Mounting force mir	١.	10 kN
F _m	max	۲.	12 kN
а	Acceleration: Device unclamped Device clamped		50 m/s ² 200 m/s ²
m	Weight		0.25 kg
Ds	Surface creepage distance	≥	30 mm
Da	Air strike distance	≥	20 mm



On-state (see Fig. 2, 3)

I _{FAVM}	Max. average on-state current	490 A	Half sine wave, T _c = 85°C
I _{FRMS}	Max. RMS on-state current	770 A	
I _{FSM}	Max. peak non-repetitive	8.5 kA	tp = 10 ms Before surge:
	surge current	27 kA	tp = 1 ms $T_c = T_j = 125^{\circ}C$
∫l ² dt	Max. surge current integral	0.36·10 ⁶ A ² s	tp = 10 ms After surge:
		0.37·10 ⁶ A ² s	tp = 1 ms $V_R \approx 0 \text{ V}$
V _F	Forward voltage drop	≤ 1.9 V	I _F = 1000 A
V _{F0}	Threshold voltage	1.4 V	Approximation for $T_j = 125^{\circ}C$
r _F	Slope resistance	0.52 mΩ	I _F = 6004000 A

Turn-on (see Fig. 4, 5)

V _{fr} Peak forward recovery voltage	≤	17 V	di/dt = 500 A/µs, T _j = 125°C	
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Turn-off (see Fig. 6, 7)

Irr	Reverse recovery current	≤	175 A	di/dt = 100 A/μs,	T _j = 125 °C,
Q _{rr}	Reverse recovery charge	≤	500 μC	I _F = 2000 A,	$V_{RM} = 2500 \text{ V},$
Err	Turn-off energy	≤	J	$R_S = 22 \Omega$,	$C_S = 0.22 \mu F$

Thermal (see Fig. 1)

Tj	Operating junction temperature range	-40125°C		
T _{stg}	Storage temperature range	-40125°C		
R _{thJC}	Thermal resistance junction to case	≤ 80 K/kW	Anode side cooled	
		≤ 80 K/kW	Cathode side cooled	F _m =
		≤ 40 K/kW	Double side cooled	10 12 kN
R _{thCH}	Thermal resistance case to heatsink	≤ 16 K/kW	Single side cooled	
		≤ 8 K/kW	Double side cooled	

Analytical function for transient thermal impedance.

$$Z_{\text{thJC}}(t) = \sum_{i=1}^{n} R_{i}(1 - e^{-t/\tau_{i}})$$

i	1	2	3	4		
R _i (K/kW) 20.95 10.57 7.15 1.3						
τ _i (s) 0.396 0.072 0.009 0.0044						
F _m = 10 12 kN Double side cooled						

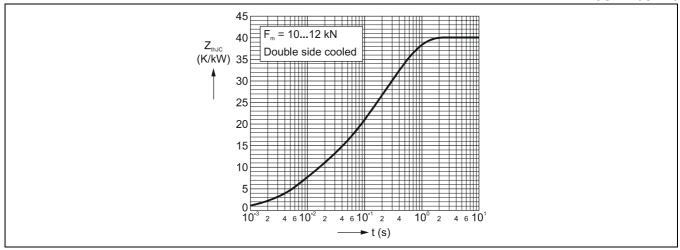


Fig. 1 Transient thermal impedance (junction-to-case) vs. time in analytical and graphical form (max. values).

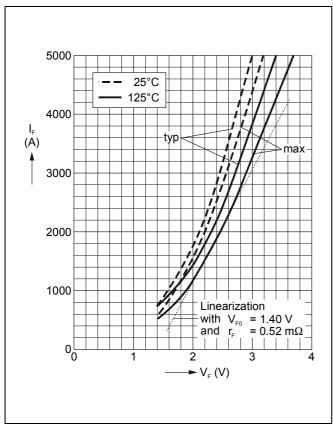


Fig. 2 Forward current vs. forward voltage (typ. and max. values) and linear approximation of max. curve at 125°C.

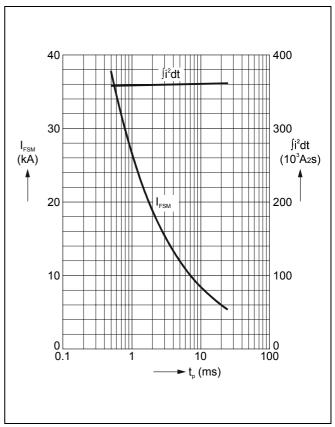


Fig. 3 Surge current and fusing integral vs. pulse width (max. values) for non-repetitive, half-sinusoidal surge current pulses.

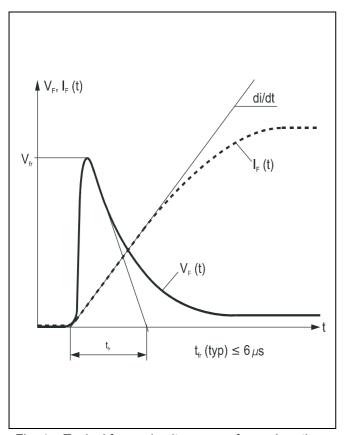


Fig. 4 Typical forward voltage waveform when the diode is turned on with a high di/dt.

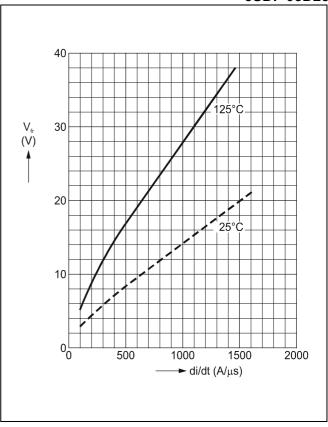


Fig. 5 Forward recovery voltage vs. turn-on di/dt (max. values).

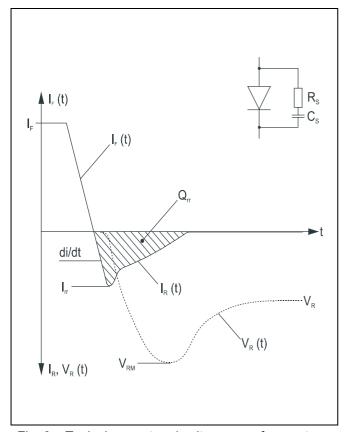


Fig. 6 Typical current and voltage waveforms at turn-off with conventional RC snubber circuit.

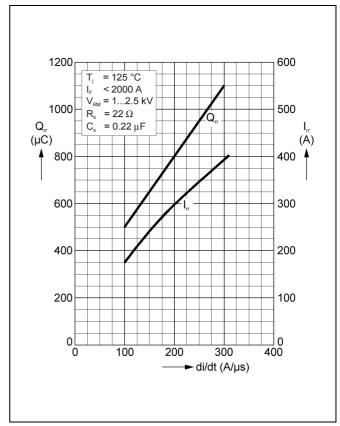


Fig. 7 Reverse recovery current and reverse recovery charge vs. di/dt (max. values).

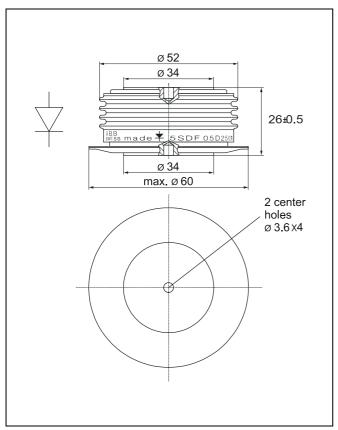


Fig. 8 Outline drawing. All dimensions are in millimeters and represent nominal values unless stated otherwise.

ABB Semiconductors AG reserves the right to change specifications without notice.



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